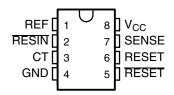
## TL7702A, TL7705A, TL7709A, TL7712A, TL7715A SUPPLY-VOLTAGE SUPERVISORS

SLVS028I - APRIL 1983 - REVISED JULY 2009

- Power-On Reset Generator
- Automatic Reset Generation After Voltage Drop
- Wide Supply-Voltage Range
- Precision Voltage Sensor
- Temperature-Compensated Voltage Reference
- True and Complement Reset Outputs
- Externally Adjustable Pulse Duration

## description/ordering information

# TL7702A, TL7709A, TL7712A, TL7715A . . . D OR P PACKAGE TL7705A . . . D, P, OR PS PACKAGE, (TOP VIEW)



#### ORDERING INFORMATION<sup>†</sup>

T <sub>A</sub>	PACKA	GE <sup>‡</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP (P)	Tube of 50	TL7702ACP	TL7702ACP
	0010 (D)	Tube of 75	TL7702ACD	770040
	SOIC (D)	Reel of 2500	TL7702ACDR	7702AC
	PDIP (P)	Tube of 50	TL7705ACP	TL7705ACP
	COIC (D)	Tube of 75	TL7705ACD	770540
	SOIC (D)	Reel of 2500	TL7705ACDR	7705AC
	SOP (PS)	Reel of 2000	TL7705ACPSR	T7705A
0°C to 70°C	PDIP (P)	Tube of 50	TL7709ACP	TL7709ACP
	0010 (D)	Tube of 75	TL7709ACD	770040
	SOIC (D)	Reel of 2500	TL7709ACDR	7709AC
	PDIP (P)	Tube of 50	TL7712ACP	TL7709ACP
	COIC (D)	Tube of 75	TL7712ACD	774040
	SOIC (D)	Reel of 2500	TL7712ACDR	7712AC
	PDIP (P)	Tube of 50	TL7715ACP	TL7715ACP
	SOIC (D)	Tube of 75	TL7715ACD	7715AC
	PDIP (P)	Tube of 50	TL7702AIP	TL7702AIP
	0010 (D)	Tube of 75	TL7702AID	770041
	SOIC (D)	Reel of 2500	TL7702AIDR	7702AI
-40°C to 85°C	PDIP (P)	Tube of 50	TL7705AIP	TL7705AIP
	SOIC (D)	Tube of 75	TL7705AID	7705 41
	SOIC (D)	Reel of 2500	TL7705AIDR	7705AI
	SOIC (D)	Reel of 2500	TL7712AIDR	7712AI

<sup>&</sup>lt;sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



<sup>&</sup>lt;sup>‡</sup> Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

## TL7702A, TL7705A, TL7709A, TL7712A, TL7715A SUPPLY-VOLTAGE SUPERVISORS

SLVS028I - APRIL 1983 - REVISED JULY 2009

#### description/ordering information (continued)

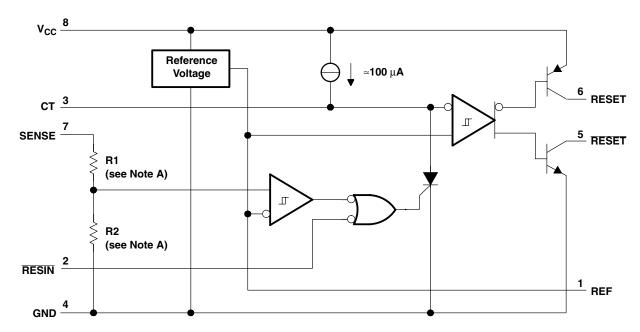
The TL77xxA family of integrated-circuit supply-voltage supervisors is designed specifically for use as reset controllers in microcomputer and microprocessor systems. The supply-voltage supervisor monitors the supply for undervoltage conditions at the SENSE input. During power up, the RESET output becomes active (low) when  $V_{CC}$  attains a value approaching 3.6 V. At this point (assuming that SENSE is above  $V_{IT+}$ ), the delay timer function activates a time delay, after which outputs RESET and RESET go inactive (high and low, respectively). When an undervoltage condition occurs during normal operation, RESET and RESET go active. To ensure that a complete reset occurs, the reset outputs remain active for a time delay after the voltage at the SENSE input exceeds the positive-going threshold value. The time delay is determined by the value of the external capacitor  $C_T$ :  $t_d = 1.3 \times 10^4 \times C_T$ , where  $C_T$  is in farads (F) and  $t_d$  is in seconds (s).

During power down and when SENSE is below  $V_{IT-}$ , the outputs remain active until  $V_{CC}$  falls below 2 V. After this, the outputs are undefined.

An external capacitor (typically 0.1  $\mu$ F) must be connected to REF to reduce the influence of fast transients in the supply voltage.

#### functional block diagram

The functional block diagram is shown for illustrative purposes only; the actual circuit includes a trimming network to adjust the reference voltage and sense-comparator trip point.



NOTES: A. TL7702A: R1 = 0  $\Omega$ , R2 = open

TL7705A: R1 = 7.8 kΩ, R2 = 10 kΩ TL7709A: R1 = 19.7 kΩ, R2 = 10 kΩ

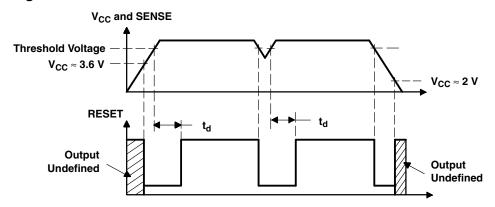
TL7712A: R1 = 32.7 k $\Omega$ , R2 = 10 k $\Omega$ 

TL7715A: R1 = 43.4 kΩ, R2 = 10 kΩ

B. Resistor values shown are nominal.



#### timing diagram



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub> (see Note 1)	20 V
Input voltage range, V <sub>I</sub> , RESIN	
Input voltage range, V <sub>I</sub> , SENSE: TL7702A (see Note 2)	
	0.3 V to 20 V
TL7709A	–0.3 V to 20 V
TL7712A, TL7715A	–0.3 V to 20 V
High-level output current, I <sub>OH</sub> , RESET	–30 mA
Low-level output current, I <sub>OL</sub> , RESET	30 mA
Package thermal impedance, $\theta_{JA}$ (see Notes 3 and 4): D package	ge 97°C/W
P packa	ge 85°C/W
PS pack	age 95°C/W
Operating virtual junction temperature, T <sub>J</sub>	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to GND.
  - 2. For proper operation of the TL7702A, the voltage applied to the SENSE terminal should not exceed V<sub>CC</sub> 1 V or 6 V, whichever is less.
  - 3. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
  - 4. The package thermal impedance is calculated in accordance with JESD 51-7.



# TL7702A, TL7705A, TL7709A, TL7712A, TL7715A SUPPLY-VOLTAGE SUPERVISORS

SLVS028I - APRIL 1983 - REVISED JULY 2009

## recommended operating conditions

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage		3.5	18	V
$V_{IH}$	High-level input voltage at RESIN		2		V
$V_{IL}$	Low-level input voltage at RESIN			0.6	V
		TL7702A	0	See Note 2	
		TL7705A	0	10	
$V_{I}$	Input voltage, SENSE	TL7709A	0	15	V
		TL7712A	0	20	
		TL7715A	0	20	
I <sub>OH</sub>	High-level output current, RESET			-16	mA
I <sub>OL</sub>	Low-level output current, RESET			16	mA
т.	Operating free-air temperature range	TL77xxAC	0	70	°C
T <sub>A</sub>	Operating nee-an temperature range	TL77xxAI	-40	85	J

NOTE 2: For proper operation of the TL7702A, the voltage applied to the SENSE terminal should not exceed  $V_{CC} - 1 \text{ V}$  or 6 V, whichever is less.

## electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETI	₽		TEST CONDITIONS†	1	7xxAC 77xxAI		UNIT
					MIN	TYP	MAX	
V <sub>OH</sub>	High-level output voltage, R	ESET		$I_{OH} = -16 \text{ mA}$	V <sub>CC</sub> -1.5			V
V <sub>OL</sub>	Low-level output voltage, RE	SET		I <sub>OL</sub> = 16 mA			0.4	V
$V_{ref}$	Reference voltage			T <sub>A</sub> = 25°C	2.48	2.53	2.58	V
			TL7702A		2.48	2.53	2.58	
			TL7705A	]	4.5	4.55	4.6	
V <sub>IT</sub> _	Negative-going input thresholds SENSE	old voltage,	TL7709A	T <sub>A</sub> = 25°C	7.5	7.6	7.7	V
	OLIVOL		TL7712A	]	10.6	10.8	11	
			TL7715A		13.2	13.2 13.5 13		
			TL7702A			10		
			TL7705A			15		
$V_{hys}$	Hysteresis, SENSE (V <sub>IT+</sub> - '	√ <sub>IT</sub> _)	TL7709A	T <sub>A</sub> = 25°C			mV	
			TL7712A	]	35			1
			TL7715A	]		45		
		DEOIN		$V_I = 2.4 \text{ V to } V_{CC}$			20	
lį	Input current	RESIN		V <sub>I</sub> = 0.4 V			-100	μΑ
		SENSE	TL7702A	$V_{ref} < V_{I} < V_{CC} - 1.5 V$		0.5	2	
I <sub>OH</sub>	High-level output current, RI	ESET	-	V <sub>O</sub> = 18 V			50	μА
I <sub>OL</sub>	Low-level output current, RE	SET		V <sub>O</sub> = 0			-50	μΑ
Icc	Supply current			All inputs and outputs open		1.8	3	mA

 $<sup>^{\</sup>dagger}$  All electrical characteristics are measured with 0.1- $\mu F$  capacitors connected at REF, CT, and  $V_{CC}$  to GND.

## switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER		TEST CO	NDITIONS†	TL TI	UNIT		
					MIN	TYP	MAX	
	Output pulse duration		$C_T = 0.1 \ \mu F$		0.65	1.2	2.6	msec
	Input pulse duration at RESIN				0.4			μs
t <sub>w(S)</sub>	Pulse duration at SENSE input to switch output	8	$V_{IH} = V_{IT-} + 200 \text{ mV},$	$V_{IL} = V_{IT-} - 200 \text{ mV}$	2			μs
t <sub>pd</sub>	Propagation delay time, RESIN	o RESET	V <sub>CC</sub> = 5 V			1	μs	
	D: "	RESET		0 N . 5			0.2	
t <sub>r</sub>	Rise time	RESET	$V_{CC} = 5 V$ ,	See Note 5			3.5	μs
	Fall time	RESET	V 5.V	Con Note 5			3.5	
t <sub>f</sub>	Fall time	RESET	$V_{CC} = 5 V$ ,	See Note 5			0.2	μS

<sup>&</sup>lt;sup>†</sup> All switching characteristics are measured with 0.1- $\mu$ F capacitors connected at REF and V<sub>CC</sub> to GND. NOTE 5: The rise and fall times are measured with a 4.7- $\mu$ C load resistor at RESET and RESET.

#### PARAMETER MEASUREMENT INFORMATION

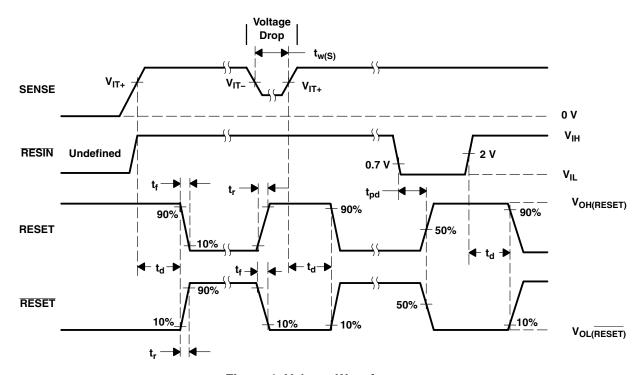
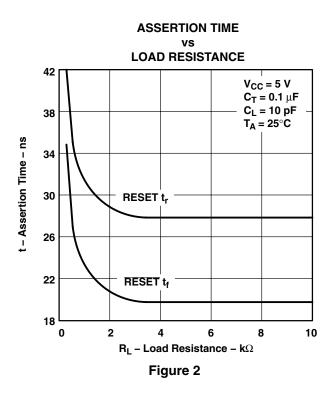
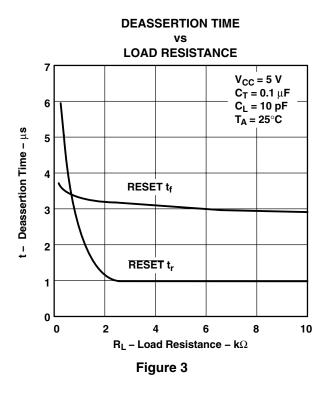
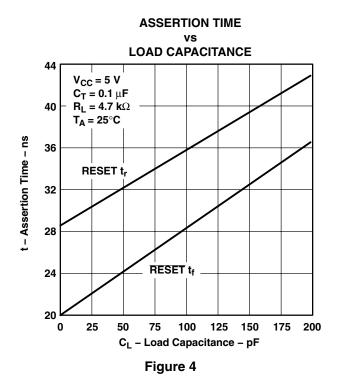


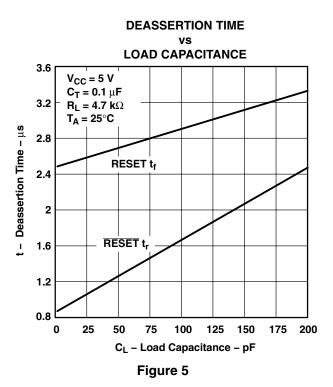
Figure 1. Voltage Waveforms

#### TYPICAL CHARACTERISTICS†









<sup>†</sup> For proper operation, both RESET and RESET should be terminated with resistors of similar value. Failure to do so may cause unwanted plateauing in either output waveform during switching.



#### **APPLICATION INFORMATION**

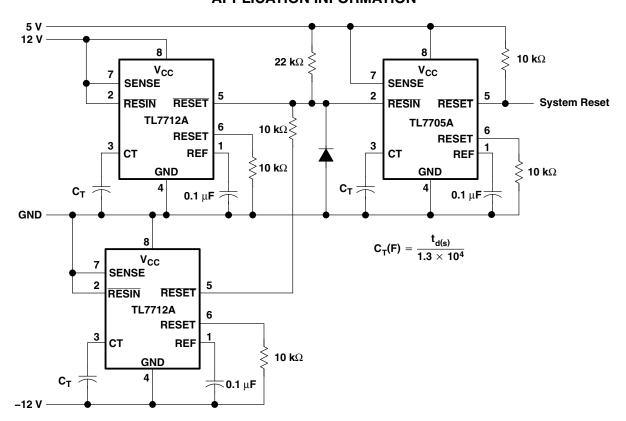


Figure 6. Multiple Power-Supply System Reset Generation

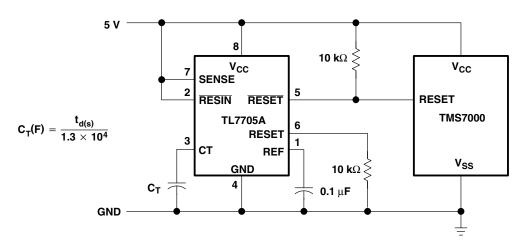


Figure 7. Reset Controller for TMS7000 System

#### **APPLICATION INFORMATION**

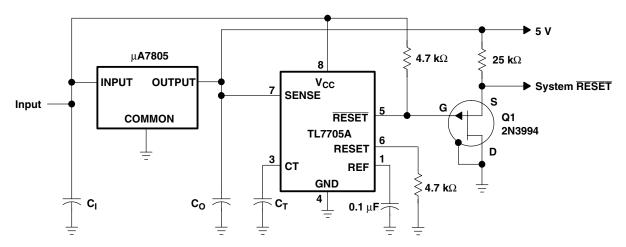


Figure 8. Eliminating Undefined States Using a P-Channel JFET

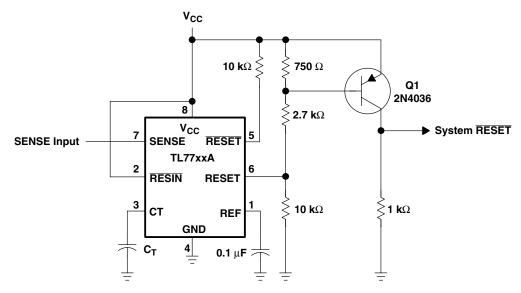


Figure 9. Eliminating Undefined States Using a pnp Transistor

#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
TL7702ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributo or Sales Office
TL7702ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribute or Sales Office
TL7702ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribute or Sales Office
TL7702ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribute or Sales Office
TL7702ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribute or Sales Office
TL7702ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribut or Sales Office
TL7702ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distribut or Sales Office
TL7702ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distribut or Sales Office
TL7702AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
TL7702AIDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
TL7702AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
TL7702AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribut or Sales Office
TL7702AIDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribut or Sales Office
TL7702AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribut or Sales Office
TL7702AIP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distribut or Sales Office
TL7702AIPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distribut or Sales Office
TL7702AMFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	Samples Not Availal
TL7702AMJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	Samples Not Availab



Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
TL7702AMJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	Samples Not Available
TL7705ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
TL7705ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
TL7705ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
TL7705ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
TL7705ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
TL7705ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
TL7705ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
TL7705ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
TL7705ACPSLE	OBSOLETE	SO	PS	8		TBD	Call TI	Call TI	Replaced by TL7705ACPSI
TL7705ACPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
TL7705ACPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
TL7705ACPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
TL7705AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
TL7705AIDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
TL7705AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
TL7705AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
TL7705AIDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
TL7705AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office



Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
TL7705AIP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor
TL7705AIPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
TL7709ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributo or Sales Office
TL7709ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributo or Sales Office
TL7709ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributo or Sales Office
TL7709ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
TL7709ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
TL7709ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
TL7709ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distribute or Sales Office
TL7709ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributo or Sales Office
TL7709AID	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	Samples Not Availab
TL7709AIP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI	Samples Not Availab
TL7712ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
TL7712ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
TL7712ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
TL7712ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribute or Sales Office
TL7712ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribute or Sales Office
TL7712ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribute or Sales Office
TL7712ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distribute or Sales Office





Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
TL7712ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
TL7712AID	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	Replaced by TL7712ACD
TL7712AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
TL7712AIP	OBSOLETE	PDIP	Р	8	-	TBD	Call TI	Call TI	Replaced by TL7712ACP
TL7715ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
TL7715ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
TL7715ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
TL7715ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
TL7715ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
TL7715AID	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	Samples Not Available
TL7715AIP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI	Samples Not Available

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



## **PACKAGE OPTION ADDENDUM**

9-Jul-2010

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**PACKAGE MATERIALS INFORMATION** 

www.ti.com 8-Jul-2011

## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL7702ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL7702AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL7705ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL7705ACPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
TL7705AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL7709ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL7712ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL7712AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

www.ti.com 8-Jul-2011



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL7702ACDR	SOIC	D	8	2500	346.0	346.0	29.0
TL7702AIDR	SOIC	D	8	2500	340.5	338.1	20.6
TL7705ACDR	SOIC	D	8	2500	340.5	338.1	20.6
TL7705ACPSR	SO	PS	8	2000	346.0	346.0	33.0
TL7705AIDR	SOIC	D	8	2500	340.5	338.1	20.6
TL7709ACDR	SOIC	D	8	2500	340.5	338.1	20.6
TL7712ACDR	SOIC	D	8	2500	340.5	338.1	20.6
TL7712AIDR	SOIC	D	8	2500	340.5	338.1	20.6

## JG (R-GDIP-T8)

#### **CERAMIC DUAL-IN-LINE**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

# FK (S-CQCC-N\*\*)

# LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



# P (R-PDIP-T8)

# PLASTIC DUAL-IN-LINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



# D (R-PDSO-G8)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



# D (R-PDSO-G8)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# PS (R-PDSO-G8)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



#### IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products	Applications
----------	--------------

Audio www.ti.com/audio Communications and Telecom www.ti.com/communications **Amplifiers** amplifier.ti.com Computers and Peripherals www.ti.com/computers dataconverter.ti.com Consumer Electronics www.ti.com/consumer-apps **Data Converters DLP® Products** www.dlp.com **Energy and Lighting** www.ti.com/energy DSP dsp.ti.com Industrial www.ti.com/industrial Clocks and Timers www.ti.com/clocks Medical www.ti.com/medical Interface interface.ti.com Security www.ti.com/security

Logic logic.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Power Mgmt power.ti.com Transportation and Automotive www.ti.com/automotive
Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID <u>www.ti-rfid.com</u>
OMAP Mobile Processors www.ti.com/omap

Wireless Connectivity www.ti.com/wirelessconnectivity

TI E2E Community Home Page e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2011, Texas Instruments Incorporated